BigTwin SuperServer SYS-621BT-DNC8R



Key Applications

Hyperconverged Infrastructure, Scale-Out Object Storage, Back-up & Recovery,

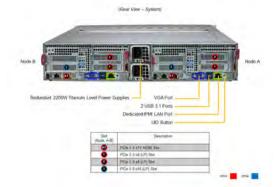
Key Features

- Socket E (LGA 4677) support 4th Gen Intel® Xeon® Scalable processors;
- Intel® C741;
- Up to 16 DIMMs ECC DDR5 Slots;
- 1 PCIe 5.0 x16 (LP) slot; 2 PCIe 5.0 x8 (LP) slot; Tool-less support; Optional M.2 NVMe Boot Controller via SCC-A2NM2241G3-B1; Internal PCIe 4.0 x8 for 2 M.2 NVMe support onboard;
- Network connectivity via AIOM (OCP 3.0 compliant);
- Built-in SAS3 Support via Broadcom 3808; IT Mode; 6 Hot-Swap 3.5" drive bays (2x PCIe 5.0 NVMe and 4x PCIe 4.0 NVMe/SAS);
- Liquid Cooling Support; 4 cooling fans per 2U enclosure, 14.9K RPM; Shared Cooling Design:
- 2200W Redundant Power Supplies Titanium Level (96%+); Shared Power Design;



Form Factor	2U Rackmount Enclosure: 449 x 88 x 774mm (17.68" x 3.47" x 30.5") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	4th Gen Intel® Xeon® Scalable processors
	Dual Socket LGA 4677 (Socket E) supported
	Intel Xeon CPU Max Series with high bandwidth memory (HBM)
	(Supports up to 350W TDP CPUs (Liquid Cooled), Supports up to 300W TDP CPUs (Aircooled)*, *CPUs (air cooled)
	with TDP over 300W are only supported under specific conditions. Contact customer support for details.)
Drive Bays	6x 3.5" hot-swap NVMe/SAS drive bays;
·	Optional HBA support via SAS3808 Adapter
Expansion Slots	2 PCIe 5.0 x8 LP slot(s)
	1 PCIe 5.0 x16 LP slot(s)
On-Board Devices	SAS: SAS3 (12Gbps) via Broadcom® 3808 (IT mode)
	Chipset: Intel® C741
	Network Connectivity: Via AIOM
	IPMI: Support for Intelligent Platform Management Interface v.2.0
	IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 RJ45 Dedicated BMC LAN port
	USB: 2 USB 3.1 port(s) (2 rear)
	Video: 1 VGA port(s)
	Others: 2x M.2 for boot drive or caching
	M.2 form factor: NVMe double-sided 22x110mm
	Note: Enterprise-grade M.2 only for caching application





System Cooling	4x 14.9K RPM Heavy Duty 8cm Fan(s)

Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)

Power Supply 2200W Redundant Power Supplies with PMBus

Dimension (W x H x L): 45 x 40 x 480 mm

System BIOS BIOS Type: AMI 32MB Flash ROM

Management SuperDoctor® 5; Watch Dog; SUM; IPMI 2.0; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; SuperCloud

Composer; Supemicro Out of Band (OOB) License (Included per Node)

PC Health Monitoring FAN: Fans with tachometer monitoring

Status monitor for speed control

Pulse Width Modulated (PWM) fan connectors

Temperature: Monitoring for CPU and chassis environment

CPU: Monitors for CPU Cores, Chipset Voltages, Memory.

8+4 Phase-switching voltage regulator

Dimensions and Weight Height: 3.47" (88 mm)

Width: 17.68" (449 mm) Depth: 30.5" (774 mm)

Gross Weight: 80.7 lbs (36.6 kg) Net Weight: 55.1 lbs (25 kg)

Packaging: 9.76" (H) x 24.65" (W) x 45.28" (D) Available Color: Black front & silver body

Operating Environment ROHS: RoHS Compliant

Operating Temperature: $10^{\circ}\text{C} \sim 35^{\circ}\text{C} (50^{\circ}\text{F} \sim 95^{\circ}\text{F})$

Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (Non-Condensing) Non-operating Relative Humidity: 5% to 95% (Non-Condensing)

Motherboard Super X13DET-B

Chassis CSE-827BD2-R2K22P